DECLARATION FOR NON-PROVISIONAL PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below at 201 et seq. beneath my name.

I believe I am the original, first and sole inventor if only one name is listed at 201 below, or an original, first and joint inventor if plural names are listed at 201 et seq. below, of the subject matter which is claimed and for which a patent is sought on the invention entitled:

METHOD FOR PREPARING A BONDING SURFACE OF A SEMICONDUCTOR LAYER OF A WAFER

and for which a patent application is attached hereto and includ	on: es amendment(s) filed on			(if i	applicable)	
was filed in the United States	s on as Application No	(declaration	on not acco	mpanying ap	plication) with	
amendment(s) filed on		(if applicable)				
was filed as PCT internation		on		a (if applicabl	and was amended	
under PCT Article 19 on				(if applicabl	(e)	
I hereby state that I have reviewamended by any amendment ref		ents of the above ident	tified applic	cation, includ	ling the claims, as	
I acknowledge the duty to discle Regulations, § 1.56.	ose information known to me to	be material to patentab	ility as defi	ned in Title 3	7, Code of Federal	
I hereby claim foreign priority be inventor's certificate listed below a filing date before that of the appropriate the control of the appropriate that the control of the appropriate that the control of the control o	w and have also identified below	w any foreign application				
EARLIEST FOREIGN AP	PLICATION(S), IF ANY, FILE	ED PRIOR TO THE FIL	LING DATI	E OF THE A	PPLICATION	
APPLICATION NUMBER	COUNTRY	DATE OF FIL (day, month, y		PRIORITY CLAIMED		
0303699	France	March 26, 2	003	⊠ YES	□ NO	
				☐ YES	□ NO	
I hereby claim the benefit und below.	er Title 35, United States Cod	e, § 119(e) of any Uni	ted States	provisional a	pplication(s) listed	
PROVISIONAL APP	FILING DATE					
60/48	39,275		July 22	, 2003	_	
I hereby claim the benefit under as the subject matter of each of provided by the first paragraph me which is material to patental the filing date of the prior applic	the claims of this application is of Title 35, United States Code oility as defined in Title 37, Code	not disclosed in the press \$112, I acknowledge de of Federal Regulation	ior United the duty to ns, § 1.56 v	States applicated disclose information of the comments of the	ition in the manner ormation known to	
NON-PROVISIONAL		1	STATUS			
APPLICATION NO.	FILING DATE			DING ABANDONED		

^{*} for use only when the application is assigned to a company, partnership or other organization.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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